

FIGs. 1 to 4

1; 51: SEMICONDUCTOR CHIP

2; 52: ELECTRODE

2a; 52a: PAD ELECTRODE

5 3; 402; 502; 53: PROTECTING FILM

301; 401; 501: WIRING FOR DRAWING STATIC ELECTRICITY

4; 54: WIRE BONDING

5; 55: LEAD

6; 56: MOLD RESIN

10

FIG. 5A

7: FINGER

10: SUBSTRATE

20: BARRIER METAL

15 21: ELECTRODE

30: PROTECTING FILM

70: UNEVENNESS OF FINGERPRINT

FIG. 1

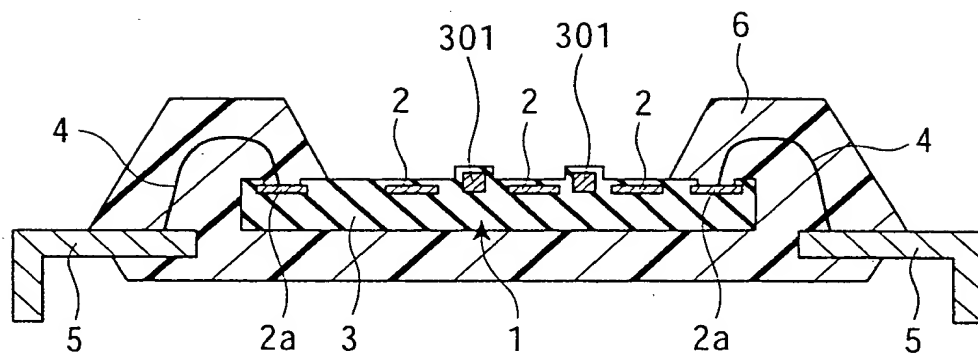


FIG. 2

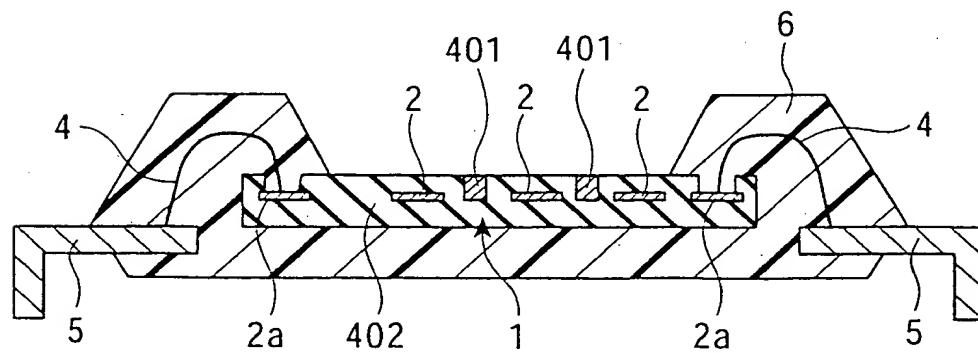


FIG. 3

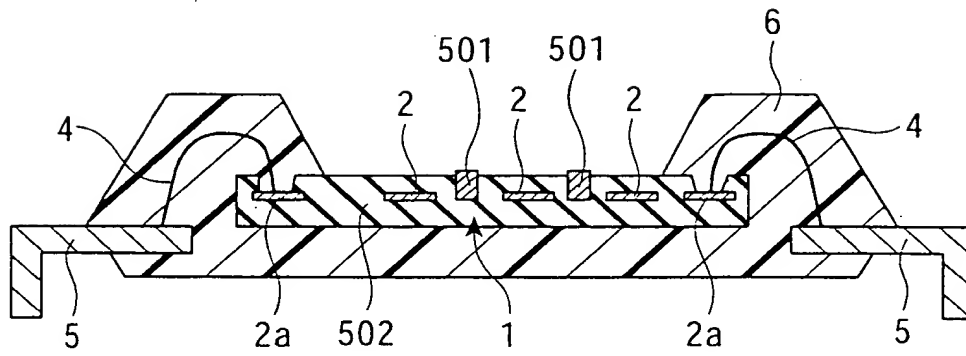


FIG. 4

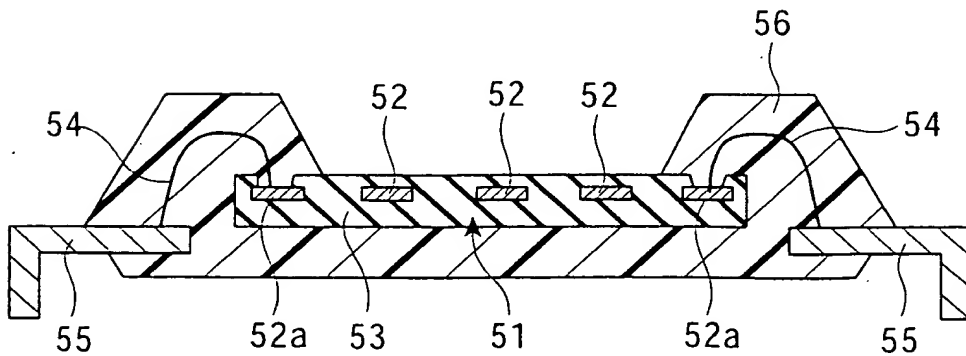


FIG. 5A

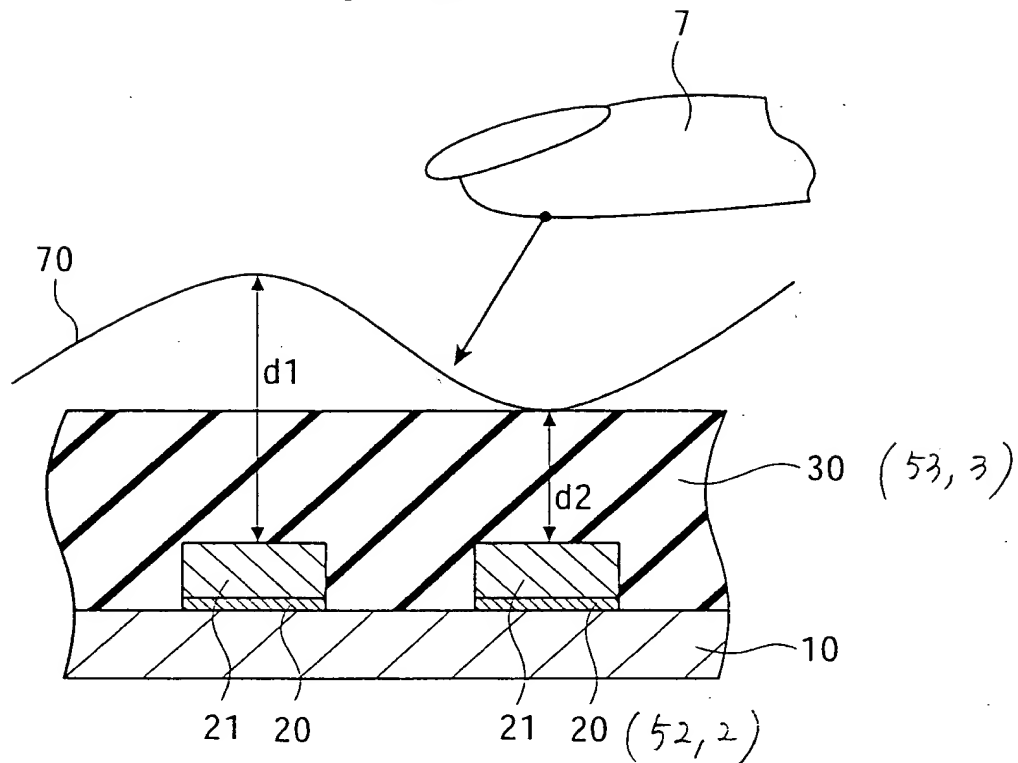


FIG. 5B

